

Applicants: Jai-Moo YOO et al.  
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**Amendments to the Claims:**

Without prejudice or disclaimer, please cancel claims 2 and 8, and amend claims 1 and 5 to read as shown below:

1. (Currently Amended) A method for manufacturing a biaxially textured metal material comprising the steps of:

depositing a biaxially textured metal layer by an electroplating process ~~selected from the group consisting of a direct current electroplating process (DC process), a pulse current electroplating process (PC process), and a periodic reverse current plating process (PR process),~~ in a plating solution comprising 100~400 g/l nickel sulfate, 0~70 g/l nickel chloride, 20~80 g/l boric acid, 0~50 g/l sodium sulfate, 0~10 g/l sodium tungstate and 0~10 g/l cobalt chloride at pH 2~4 and 50~80°C on the surface of a metal substrate having a single-crystalline or a quasi-single-crystalline orientation; and

peeling the deposited biaxially textured metal layer off the metal substrate after electroplating wherein the peeled biaxially textured metal layer has substantially the same texture orientation as that of the metal substrate.

2. (Canceled).

3. (Currently Amended) The method for manufacturing a biaxially textured metal material according to claim 1, wherein the biaxially textured metal layer is deposited in a plating solution at a cathode current density of 3~20 A/dm<sup>2</sup> using ~~the~~ a

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direct current electroplating process (DC process), the deposited metal layer having a texture fraction (TF) of 0.97 or more on the (001) plane.

4. (Currently amended) The method for manufacturing a biaxially textured metal material according to claim 1, wherein the biaxially textured metal layer is deposited in a plating solution under conditions of a cathode current density of 3~20 A/dm<sup>2</sup>, a cathode current time of 1~100 msec and a down time of 1~100 msec using ~~the~~ a pulse current electroplating process (PC process), the deposited metal layer having a texture fraction (TF) of 0.97 or more on the (001) plane.

5. (Currently Amended) The method for manufacturing a biaxially textured metal material according to claim 1, wherein the biaxially textured metal layer is deposited in a plating solution under conditions of a cathode current density of 3~20 A/dm<sup>2</sup>, a cathode current time of 1~100 msec and an anode current time of 1~100 msec using ~~the~~ a periodic reverse current plating process (PR process), the deposited ~~pure metal or alloy~~ layer having a texture fraction (TF) of 0.97 or more on the (001) plane.

6. (Canceled).

7. (Canceled).

8. (Canceled).